

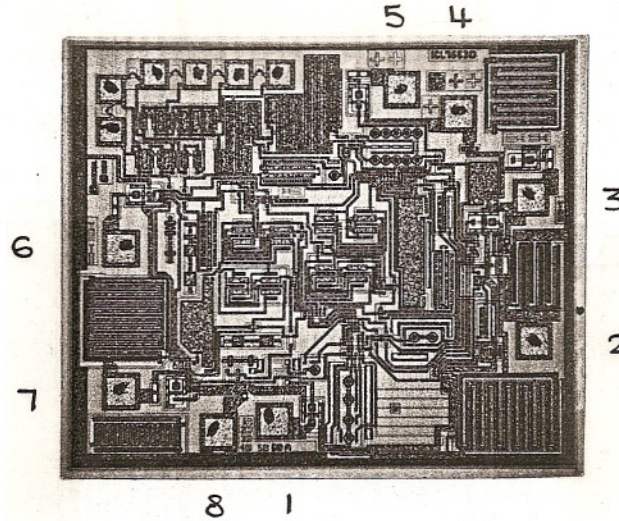


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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



<u>PAD NO</u>	<u>FUNCTIONS</u>
1	Sense
2	V Out 2
3	V Out 1
4	GND
5	SHDN
6	V Set
7	V TC
8	V+ In

Topside Metal: Al

Backside: Si

Backside Potential:

Mask Ref:

Bond Pads : .004 min

APPROVED BY: CB

MFG: Harris

DIE SIZE: .065" x .076"

THICKNESS: .019"

DATE: 2/6/01

P/N: ICL7663D